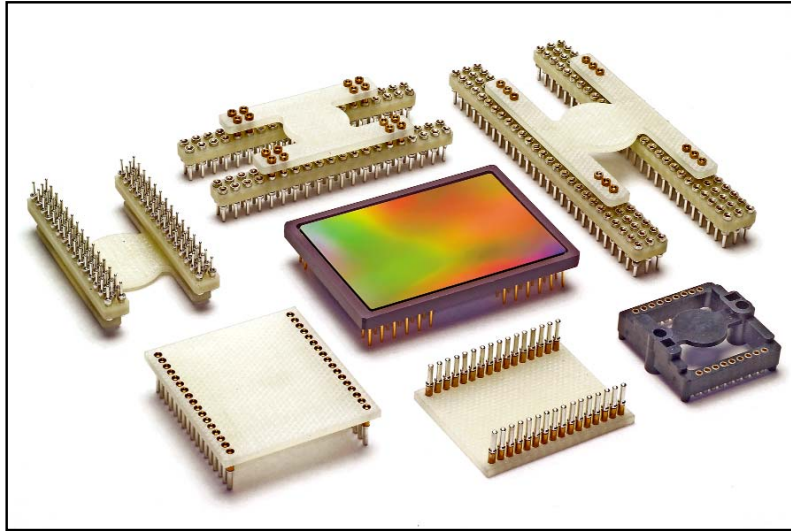


MAX solutions

Socket Solutions for CCD & CMOS Imagers



Mill-Max offers a comprehensive range of solutions for socketing CCD & CMOS Imagers having leaded (pinned) packages.

- Through-hole and surface mount sockets with pin spacings on .100", 2mm, .070", .050", 1mm or 0.8mm grids.
- Through-hole sockets available with solder preforms for intrusive reflow soldering.
- Molded high temp. or machined FR-4 insulators.
- Receptacle carriers that eliminate the socket insulator for extremely low profile applications.
- Pins are precision-machined copper alloy and incorporate a beryllium copper spring contact. Heat treated BeCu is the best electrical spring contact material to ensure security of the imager while maintaining its pluggability.
- Available with RoHS compliant materials.

For more information, please visit mill-max.com/PR557.

(07/09-557)

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